

Bill of Materials

TI DESIGNS

TIDA-00404

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	U1		HTSSOP48-DCA ROHS	TEXAS INSTRUMENTS	TAS5754MDCA	HTSSOP48-DCA
2	1	U2		20W FILTER FREE STEREO CLASS-D AUDIO PWR AMP HTSSOP32-DAP ROHS	TEXAS INSTRUMENTS	TAS5760xDAP	HTSSOP32-DAP
3	1	U3		SERIAL EEPROM I2C 256K 400kHz MSOP8-MS ROHS	MICROCHIP	24LC256-I/MS	MSOP8-MS
4	4	C1, C10, C11, C13	1.0uf	CAP SMD0402 CERM 1.0UFD 16V 10% X5R ROHS	TDK CORP	C1005X5R1C105K050BC	
5	4	C2, C3, C14, C15	0.22uf	CAP SMD0402 CERM 0.22UFD 16V X7R 10% ROHS	MURATA	GRM155R71C224KA12D	
6	3	C4, C12, C52	1.0uf	CAP SMD0603 CERM 1.0UFD 50V 10% X7R ROHS	TAIYO YUDEN	UMK107AB7105KA-T	
7	3	C5, C16, C30	0.1uf	CAP SMD0402 CERM 0.1ufd 50V 10% X7R ROHS	TDK CORP	C1005X7R1H104K	
8	4	C6, C7, C17, C18	22uf	CAP SMD0805 CERM 22UFD 35V 20% X5R ROHS	TDK	C2012X5R1V226M125AC	
9	8	C8, C9, C19, C20, C35, C36, C37, C38	.22uf	CAP SMD0603 CERM 0.22UFD 50V 10% X7R ROHS	MURATA	GCM188R71H224KA64D	
10	4	C21, C22, C23, C24	4700pf	CAP SMD0603 CERM 4700PFD 50V 5% COG ROHS	MURATA	GRM1885C1H472JA01D	
11	5	C31, C32, C33, C34, C50	1.0uf	CAP SMD0402 CERM 1.0UFD 10V 10% X5R ROHS	TDK CORP	C1005X5R1A105K	
12	2	C39, C41	0.1uf	CAP SMD0603 CERM 0.1UFD 50V 10% X7R ROHS	MURATA	GRM188R71H104KA93D	
13	2	C43, C44	0.68uf	CAP SMD0805 CERM 0.68ufd 50V 10% X7R ROHS	TDK	C2012X7R1H684K	
14	2	C40, C42	390uf	CAP SMD ELECT 390ufd 35V 20% CL ROHS	NICHICON	UCL1V391MNL1GS	
15	6	C60, C61, C62, C63, C64, C65	.01uf	CAP SMD0603 CERM 0.01UFD 50V 10% X7R ROHS	MURATA	GRM188R71H103KA01D	
16	4	R1, R24, R25, R26	0R	ZERO OHM JUMPER SMT 0402 0 OHM 1/16W,5% ROHS	STACKPOLE ELECTRONICS	RMCF0402ZTOR00	
17	3	R2, R3, R4	100K	RESISTOR SMD0402 THICK FILM 100K OHMS 1/16W 1% ROHS	PANASONIC	ERJ-2RKF1003X	
18	8	R5, R10, R11, R13, R20, R21, R22, R23	10K	RESISTOR SMD0402 10.0K OHMS 1% 1/16W ROHS	VISHAY	CRCW040210K0FKED	
19	1	R12	0R	RESISTOR SMD1206 0.0 OHM 5% 1/4W ROHS	PANASONIC	ERJ-8GEY0R00V	

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20	6	R30, R31, R32, R33, R34, R35	3.3R	RESISTOR SMD0603 3.3 OHMS 5% 1/10W ROHS	PANASONIC	ERJ-3GEYJ3R3V	
21	4	FB1, FB2, FB3, FB4		CHIP NOISE FILTER SMD0806 300 OHMS@100MHz 3.1A 24 OHMS ROHS	MURATA	NFZ2MSM601SN10L	
22	2	L1, L2		INDUCTOR SERIES 11RHBP/A7503AY 4.7uH/5.1A ROHS	TOKO	A7503AY-4R7M	
23	3	SUB, OUTA, OUTB		JACK JST-VH RA 2-PIN 3.96mmLS ROHS	JST	B2PS-VH(LF)(SN)	
24	1	J1		CONNECTOR SMT/THU 100 POS+GND MATE HEIGHT 5mm ROHS	SAMTEC	QTS-050-01-F-D-A	
25	1	VIN		BINDING POST, RED, 15A ECONO ROHS	KEYSTONE ELECTRONICS	7006	
26	1	GND		BINDING POST, BLACK, 15A ECONO ROHS	KEYSTONE ELECTRONICS	7007	
27	1	JP1		BUS WIRE JUMPER 22AWG NON-INSULATED 22.5mm LENGTH ROHS	ALPHA WIRE COMPANY	298 SV001 12.5MM	
28	2	STANDOFFS		STANDOFF M3x30mm 6mm DIA HEX ALUM F-F ROHS	MCMaster-CARR	95947A060	
29	4	STANDOFF SCREWS		SCREW M3x8 PHILIPS PANHEAD STAINLESS STEEL ROHS	MCMaster-CARR	92000A118	
30	2	STANDOFF WASHERS		WASHER SPLIT-LOCK M3 6.2mm OD 0.7mm THICK STAINLESS STEEL ROHS	MCMaster-CARR	92148A150	

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